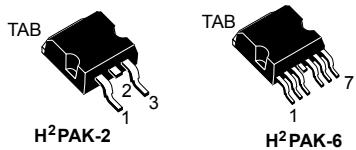
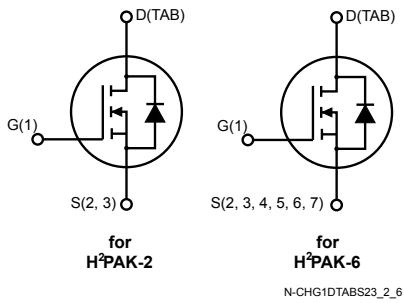


### Automotive-grade N-channel 100 V, 2.1 mΩ typ., 180 A STripFET F7 Power MOSFETs in an H<sup>2</sup>PAK-2 and H<sup>2</sup>PAK-6 packages

#### Features



Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STH315N10F7-2	100 V	2.3 mΩ	
STH315N10F7-6			180 A



- AEC-Q101 qualified
- Among the lowest R<sub>DS(on)</sub> on the market
- Excellent FoM (figure of merit)
- Low C<sub>rss</sub>/C<sub>iss</sub> ratio for EMI immunity
- High avalanche ruggedness

#### Applications

- Switching applications

#### Description

These N-channel Power MOSFETs utilize STripFET F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Product status	
STH315N10F7-2	
STH315N10F7-6	

Product summary	
Order code	STH315N10F7-2
Marking	315N10F7
Package	H <sup>2</sup> PAK-2
Packing	Tape and reel
Order code	STH315N10F7-6
Marking	315N10F7
Package	H <sup>2</sup> PAK-6
Packing	Tape and reel

## 1

## Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	100	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D$ <sup>(1)</sup>	Drain current (continuous) at $T_C = 25^\circ\text{C}$	180	A
$I_D$ <sup>(1)</sup>	Drain current (continuous) at $T_c = 100^\circ\text{C}$	180	A
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	720	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	315	W
	Derating factor	2.1	W/ $^\circ\text{C}$
$E_{AS}$ <sup>(3)</sup>	Single pulse avalanche energy	1	J
$T_j$	Operating junction temperature range	-55 to 175	$^\circ\text{C}$
$T_{stg}$	Storage temperature range		

1. Current limited by package.
2. Pulse width limited by safe operating area.
3. Starting  $T_j=25^\circ\text{C}$ ,  $I_D=60\text{ A}$ ,  $V_{DD}=50\text{ V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	0.48	$^\circ\text{C/W}$
$R_{thJB}$ <sup>(1)</sup>	Thermal resistance, junction-to-board	35	$^\circ\text{C/W}$

1. When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board.

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified)

**Table 3. On/Off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	100			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, T_C = 125^\circ\text{C}$ (1)			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.5	3.5	4.5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$		2.1	2.3	$\text{m}\Omega$

1. Defined by design, not subject to production test.

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	12800	-	pF
$C_{oss}$	Output capacitance		-	3500	-	pF
$C_{rss}$	Reverse transfer capacitance		-	170	-	pF
$Q_g$	Total gate charge	$V_{DD} = 50 \text{ V}, I_D = 180 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$	-	180	-	nC
$Q_{gs}$	Gate-source charge		-	78	-	nC
$Q_{gd}$	Gate-drain charge		(see Figure 15. Test circuit for gate charge behavior)	-	34	-

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 50 \text{ V}, I_D = 90 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	62	-	ns
$t_r$	Rise time		-	108	-	ns
$t_{d(\text{off})}$	Turn-off delay time		-	148	-	ns
$t_f$	Fall time		-	40	-	ns

**Table 6. Source-drain diode**

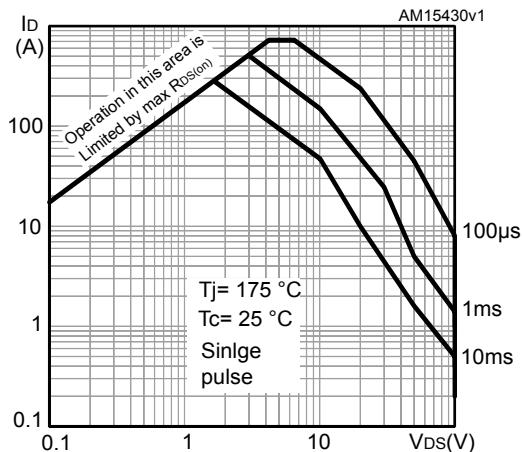
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		180	A
$I_{SDM}$ (1)	Source-drain current (pulsed)		-		720	A
$V_{SD}$ (2)	Source-drain current	$I_{SD} = 60 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_{SD} = 180 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$	-	85		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 80 \text{ V}$ , $T_J = 150 \text{ }^\circ\text{C}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	200		nC
$I_{RRM}$	Reverse recovery current		-	4.7		A

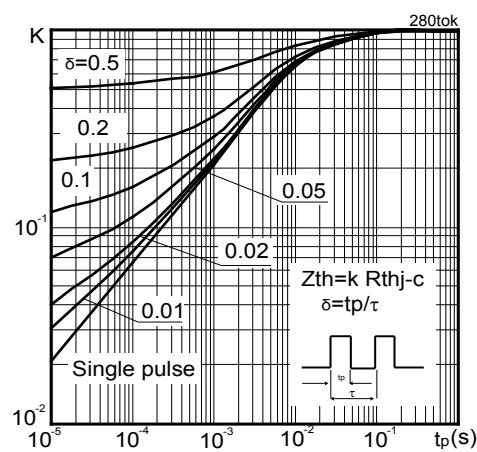
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration=300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

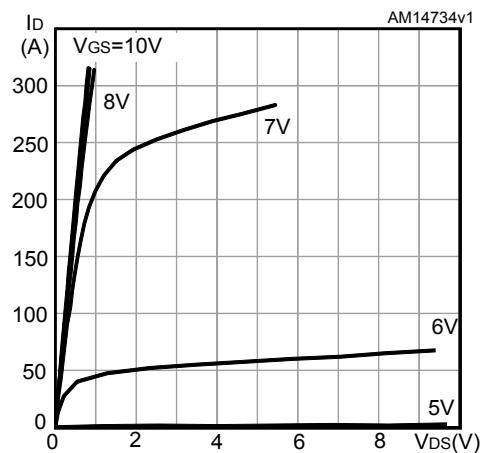
**Figure 1. Safe operating area**



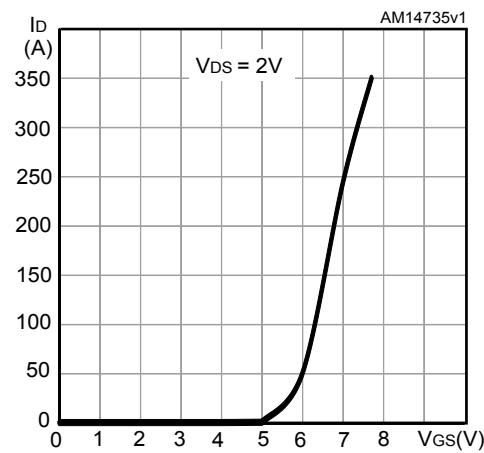
**Figure 2. Thermal impedance**



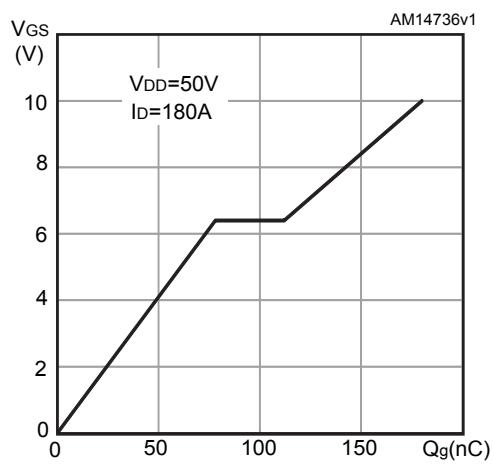
**Figure 3. Output characteristics**



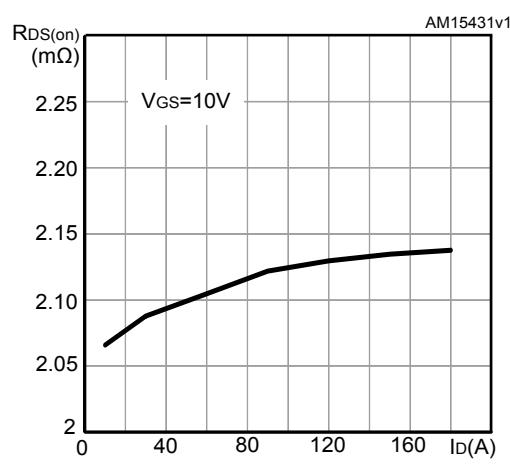
**Figure 4. Transfer characteristics**

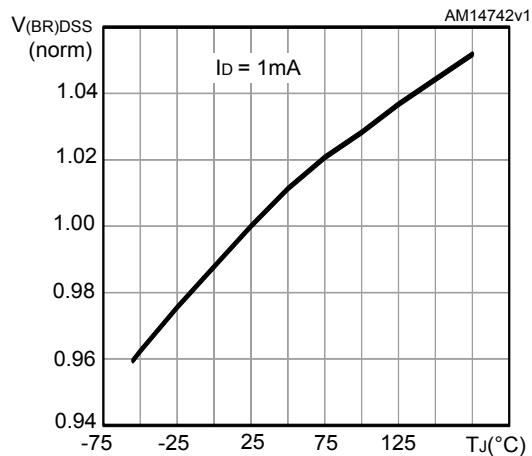
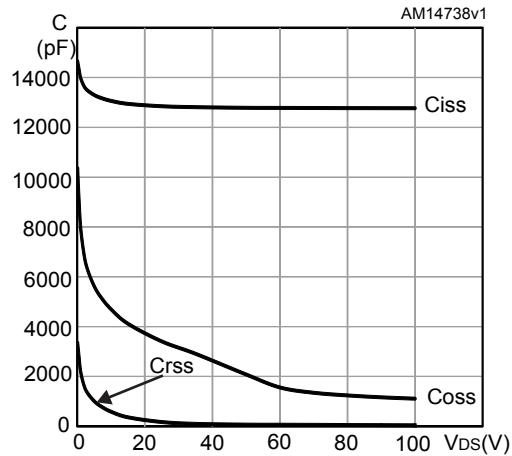
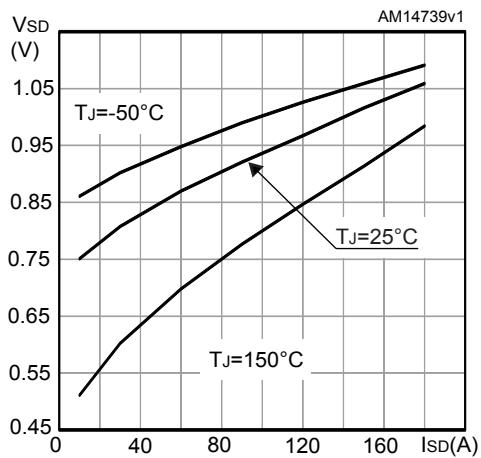
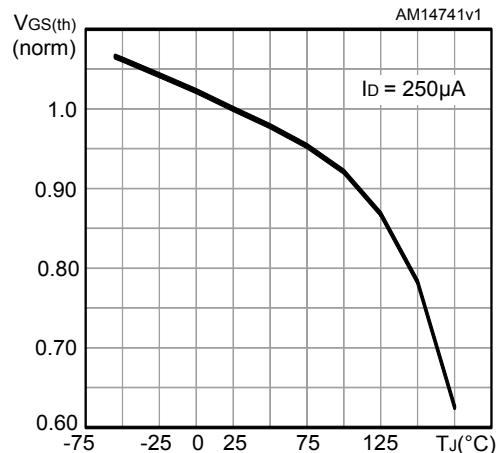
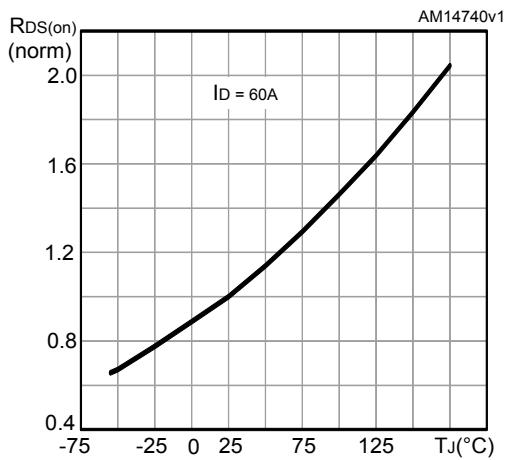


**Figure 5. Gate charge vs gate-source voltage**



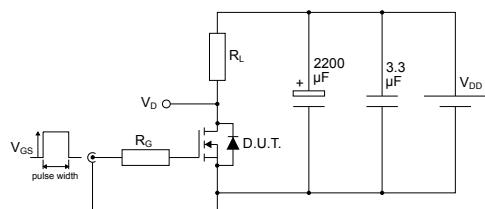
**Figure 6. Static drain-source on-resistance**



**Figure 7. Normalized  $V_{(BR)DSS}$  vs temperature**

**Figure 8. Capacitance variations**

**Figure 9. Source-drain diode forward characteristics**

**Figure 10. Normalized gate threshold voltage vs temperature**

**Figure 11. Normalized on-resistance vs temperature**


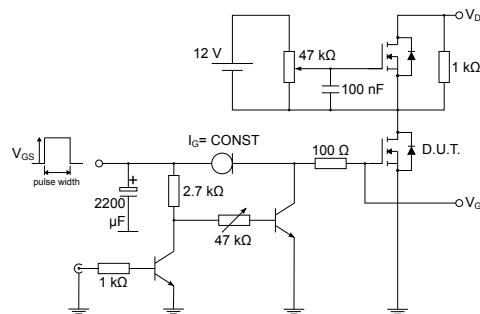
### 3 Test circuits

**Figure 12.** Test circuit for resistive load switching times



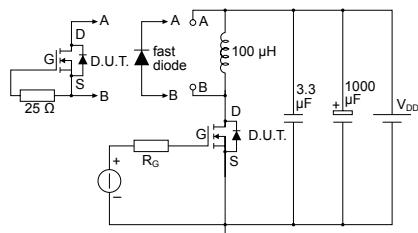
AM01468v1

**Figure 13.** Test circuit for gate charge behavior



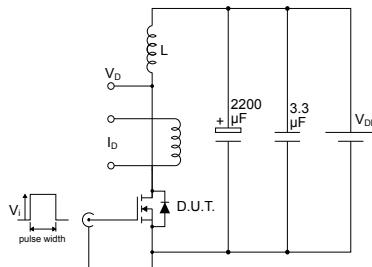
AM01469v1

**Figure 14.** Test circuit for inductive load switching and diode recovery times



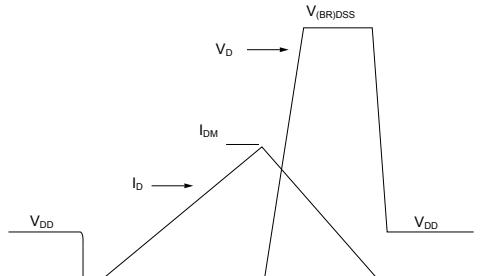
AM01470v1

**Figure 15.** Unclamped inductive load test circuit



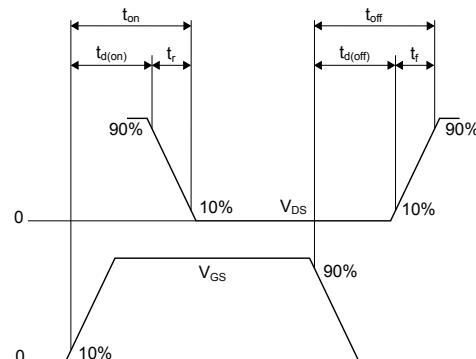
AM01471v1

**Figure 16.** Unclamped inductive waveform



AM01472v1

**Figure 17.** Switching time waveform



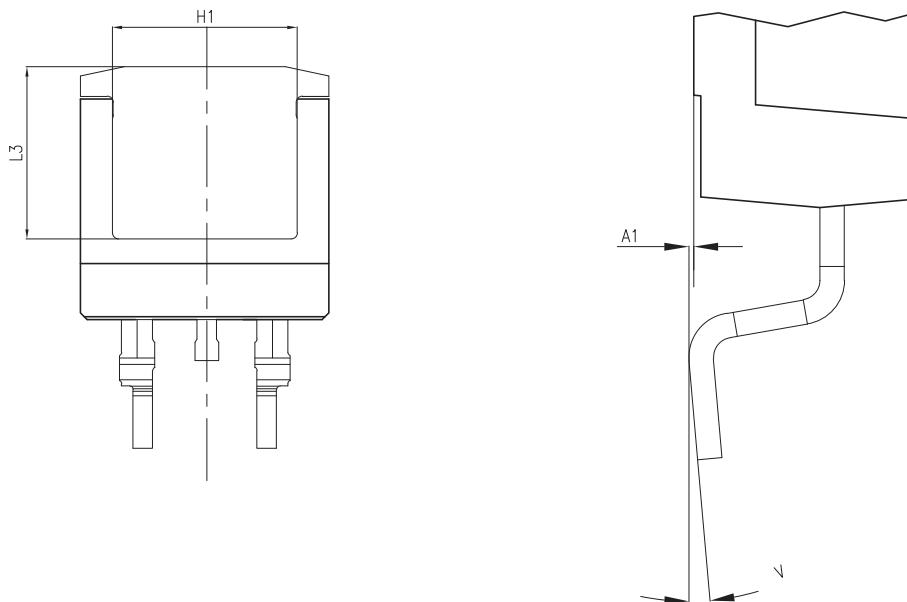
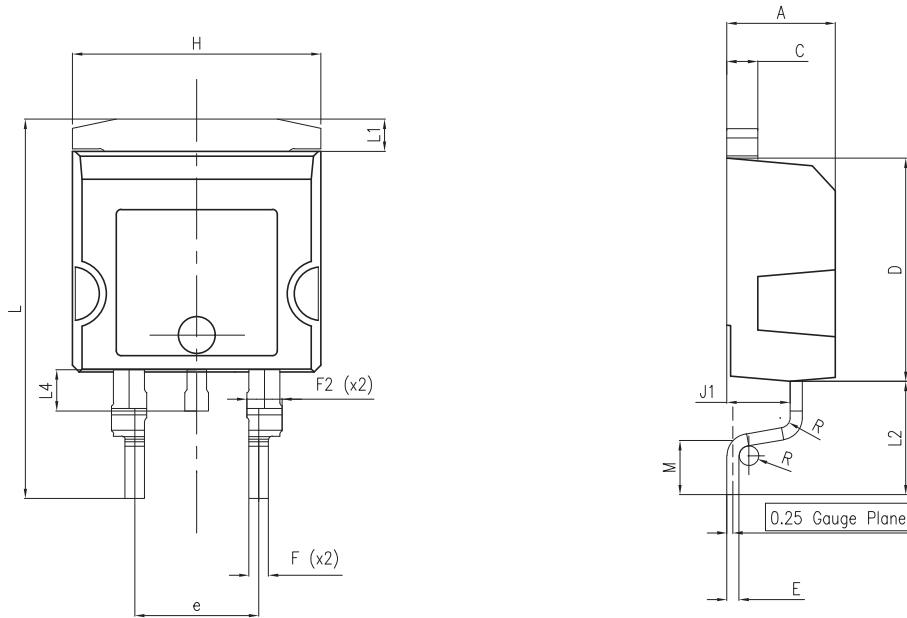
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 H<sup>2</sup>PAK-2 package information

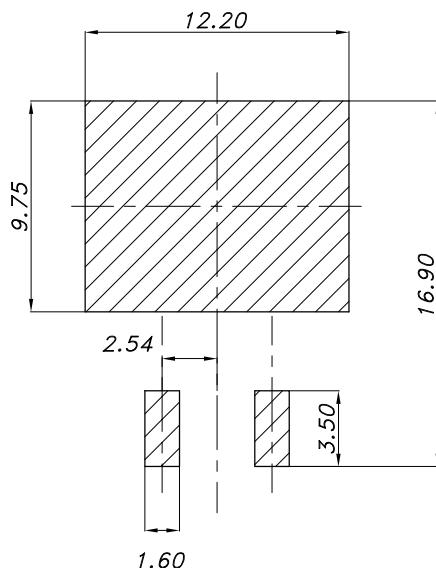
Figure 18. H<sup>2</sup>PAK-2 package outline



8159712\_9

Table 7. H<sup>2</sup>PAK-2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.70
A1	0.03		0.20
C	1.17		1.37
D	8.95		9.35
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
F2	1.14		1.70
H	10.00	-	10.40
H1	7.40		7.80
J1	2.49		2.69
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.50		1.70
M	2.60		2.90
R	0.20		0.60
V	0°		8°

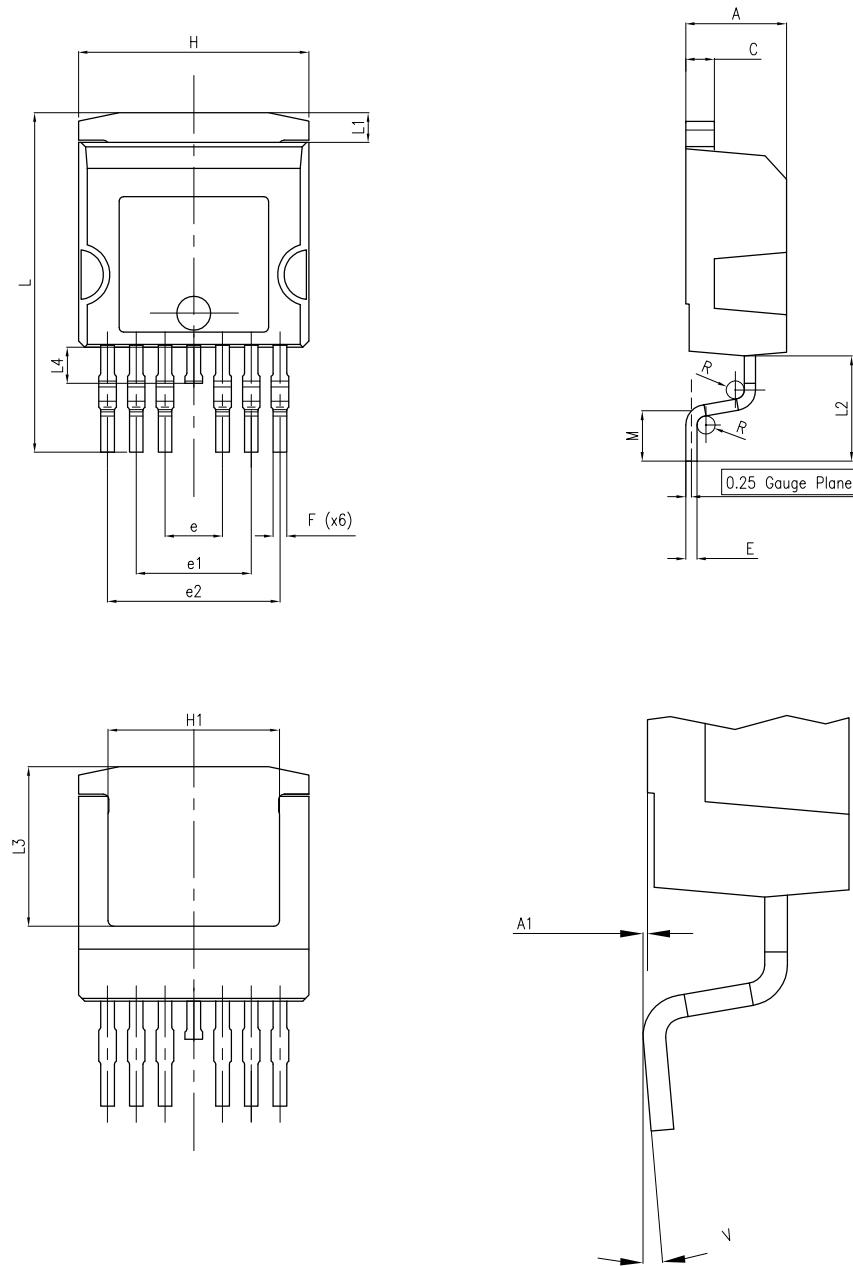
Figure 19. H<sup>2</sup>PAK-2 recommended footprint

8159712\_9

Note: Dimensions are in mm.

## 4.2 H<sup>2</sup>PAK-6 package information

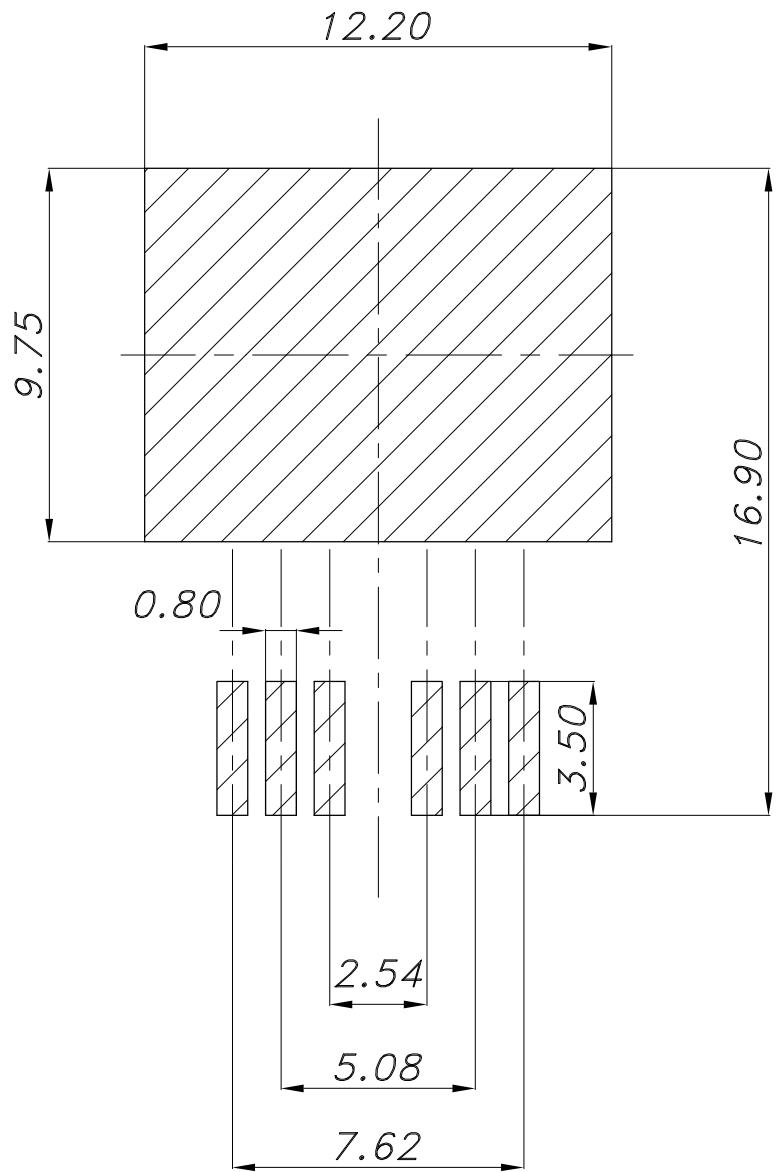
Figure 20. H<sup>2</sup>PAK-6 package outline



8159693\_Rev\_8

**Table 8. H<sup>2</sup>PAK-6 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.70
A1	0.03		0.20
C	1.17		1.37
e	2.34	2.54	2.74
e1	4.88		5.28
e2	7.42		7.82
E	0.45		0.60
F	0.50		0.70
H	10.00		10.40
H1	7.40		7.80
L	14.75		15.25
L1	1.27		1.40
L2	4.35		4.95
L3	6.85		7.25
L4	1.50		1.75
M	1.90		2.50
R	0.20		0.60
V	0°		8°

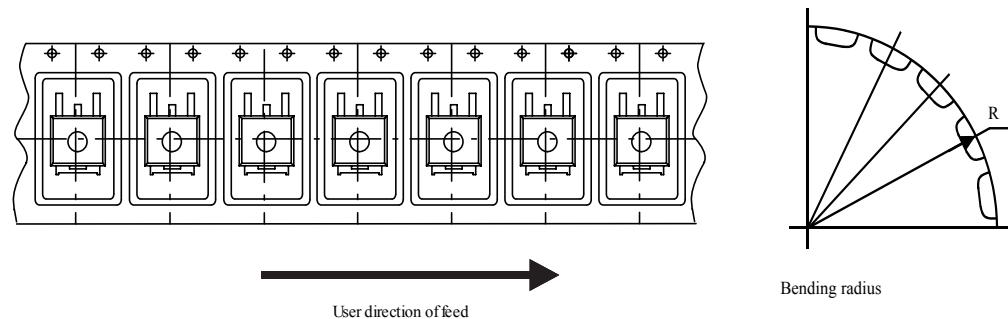
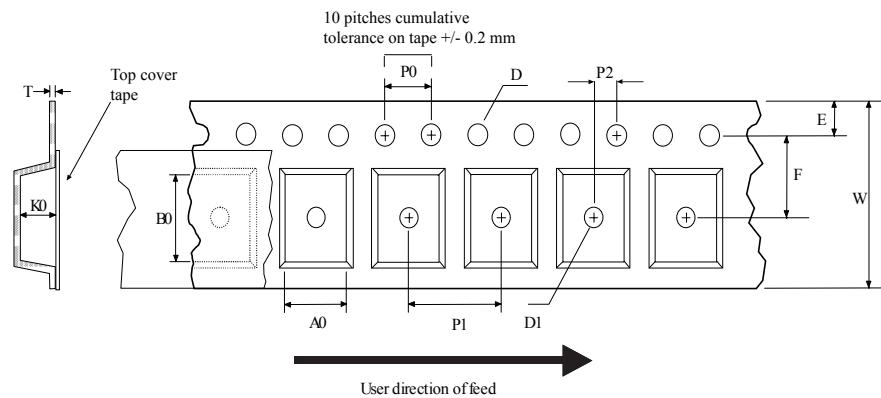
Figure 21. H<sup>2</sup>PAK-6 recommended footprint

footprint\_Rev\_8

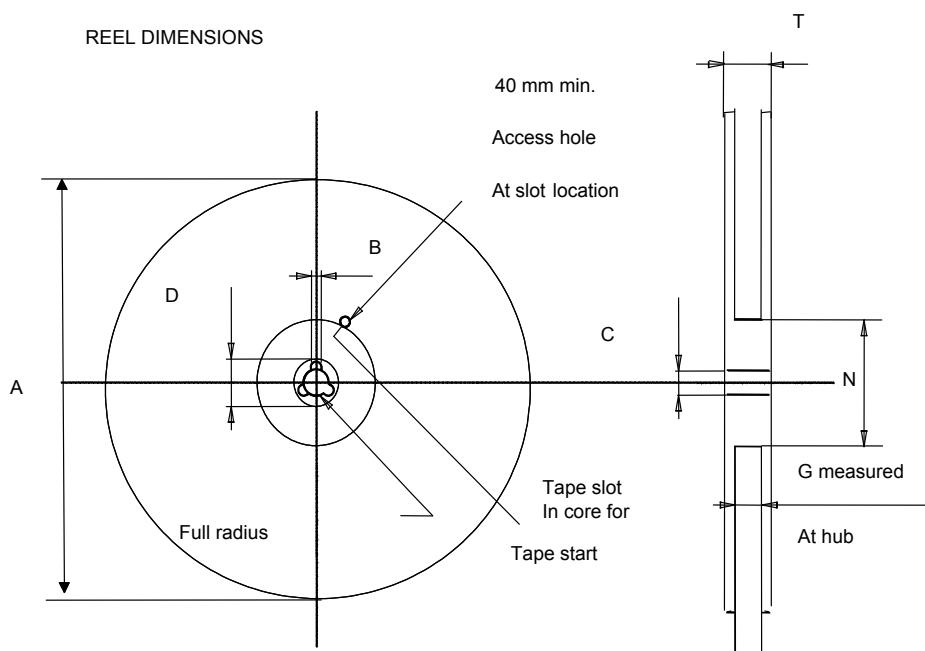
Note: Dimensions are in mm.

## 4.3 Packing information

**Figure 22. Tape outline**



**Figure 23. Reel outline**



**Table 9. Tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base quantity	1000
P2	1.9	2.1		Bulk quantity	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## Revision history

**Table 10. Document revision history**

Date	Version	Changes
02-Aug-2013	1	Initial release.
03-Sep-2013	2	– Modified: <i>Table 1</i> , RDS(on) typical value in <i>Table 4</i> – Minor text changes
27-May-2014	3	– Modified: title and <i>Features</i> in cover page – Updated: <i>Section 4: Package mechanical data</i> – Minor text changes
12-Sep-2014	4	– Modified: title, features and description in cover page.
03-May-2021	5	Updated <i>Table 1. Absolute maximum ratings</i> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings .....</b>	<b>2</b>
<b>2</b>	<b>Electrical characteristics.....</b>	<b>3</b>
2.1	Electrical characteristics (curves) .....	5
<b>3</b>	<b>Test circuits .....</b>	<b>7</b>
<b>4</b>	<b>Package information.....</b>	<b>8</b>
4.1	H <sup>2</sup> PAK-2 package information .....	8
4.2	H <sup>2</sup> PAK-6 package information .....	10
4.3	H <sup>2</sup> PAK-2 and H <sup>2</sup> PAK-6 packing information .....	13
	<b>Revision history .....</b>	<b>15</b>

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2021 STMicroelectronics – All rights reserved